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[Vishay/Siliconix](#)
[SI2300DS-T1-GE3](#)

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Si2300DS

Vishay Siliconix

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (Typ.)
30	0.068 at V _{GS} = 4.5 V	3.6 ^a	3 nC
	0.085 at V _{GS} = 2.5 V	3.4	

FEATURES

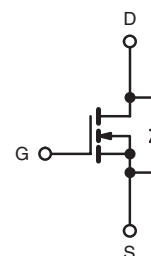
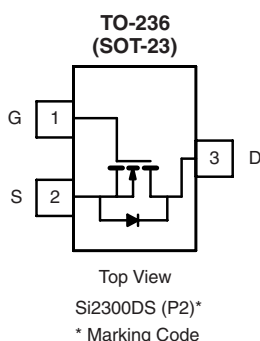
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- DC/DC Converter for Portable Devices
- Load Switch



Ordering Information: Si2300DS-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted			
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	± 12	
Continuous Drain Current (T _J = 150 °C)	I _D	T _C = 25 °C	3.6 ^a
		T _C = 70 °C	3.0
		T _A = 25 °C	3.1 ^{b, c}
		T _A = 70 °C	2.5 ^{b, c}
Pulsed Drain Current	I _{DM}	15	A
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	
		T _A = 25 °C	0.9 ^{b, c}
Maximum Power Dissipation	P _D	T _C = 25 °C	1.7
		T _C = 70 °C	1.1
		T _A = 25 °C	1.1 ^{b, c}
		T _A = 70 °C	0.7 ^{b, c}
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C
Soldering Recommendations (Peak Temperature) ^{d, e}		260	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	90	115	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	60	75	

Notes:

- Package limited
- Surface mounted on 1" x 1" FR4 board.
- t = 5 s.
- Maximum under steady state conditions is 130 °C/W.

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SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted							
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	30			V	
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = 250\text{ }\mu\text{A}$		21		mV/ $^\circ\text{C}$	
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$			-3.2			
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	0.6		1.5	V	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 12\text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$			1	μA	
		$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$			10		
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	10			A	
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}, I_D = 2.9\text{ A}$		0.055	0.068	Ω	
		$V_{GS} = 2.5\text{ V}, I_D = 2.6\text{ A}$		0.070	0.085		
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15\text{ V}, I_D = 2.9\text{ A}$		13		S	
Dynamic^b							
Input Capacitance	C_{iss}	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		320		pF	
Output Capacitance	C_{oss}			45			
Reverse Transfer Capacitance	C_{rss}			19			
Total Gate Charge	Q_g	$V_{DS} = 15\text{ V}, V_{GS} = 10\text{ V}, I_D = 3.1\text{ A}$		6.5	10	nC	
			$V_{DS} = 15\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 3.1\text{ A}$		3		4.5
Q_{gs}		0.8					
Q_{gd}		0.5					
Gate Resistance	R_g	$f = 1\text{ MHz}$	0.6	3.2	6.4	Ω	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}, R_L = 6\text{ }\Omega$ $I_D \cong 2.5\text{ A}, V_{GEN} = 4.5\text{ V}, R_g = 1\text{ }\Omega$		10	15	ns	
Rise Time	t_r			15	25		
Turn-Off Delay Time	$t_{d(off)}$			20	30		
Fall Time	t_f			11	20		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 15\text{ V}, R_L = 6\text{ }\Omega$ $I_D \cong 2.5\text{ A}, V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$		5	10		
Rise Time	t_r			12	20		
Turn-Off Delay Time	$t_{d(off)}$			15	25		
Fall Time	t_f			10	15		
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^\circ\text{C}$			1.4	A	
Pulse Diode Forward Current	I_{SM}				15		
Body Diode Voltage	V_{SD}	$I_S = 2.5\text{ A}, V_{GS} = 0\text{ V}$		0.8	1.2	V	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = 2.5\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$		11	20	ns	
Body Diode Reverse Recovery Charge	Q_{rr}				5	10	nC
Reverse Recovery Fall Time	t_a				7		ns
Reverse Recovery Rise Time	t_b				4		

Notes:

 a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.

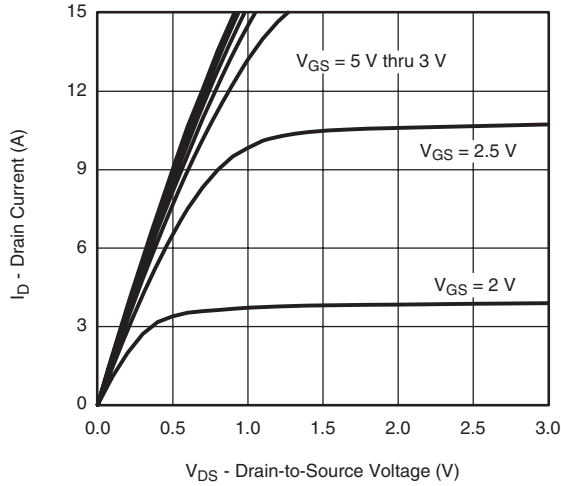
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

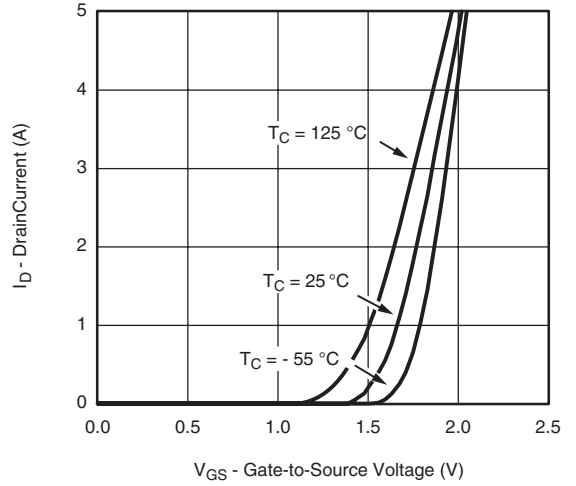


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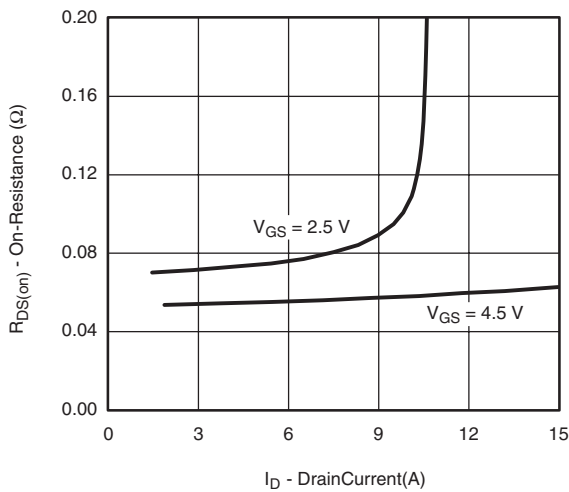
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



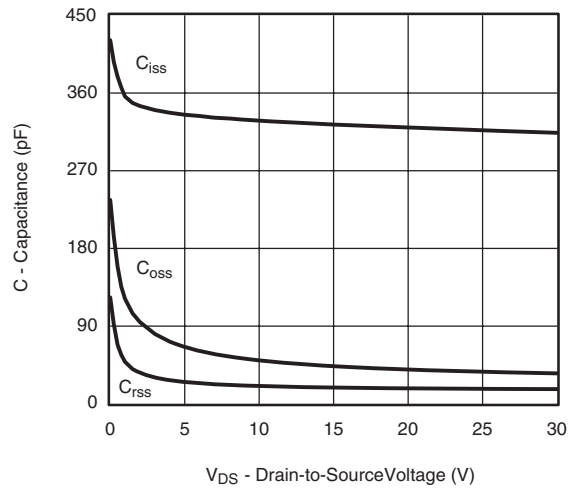
Output Characteristics



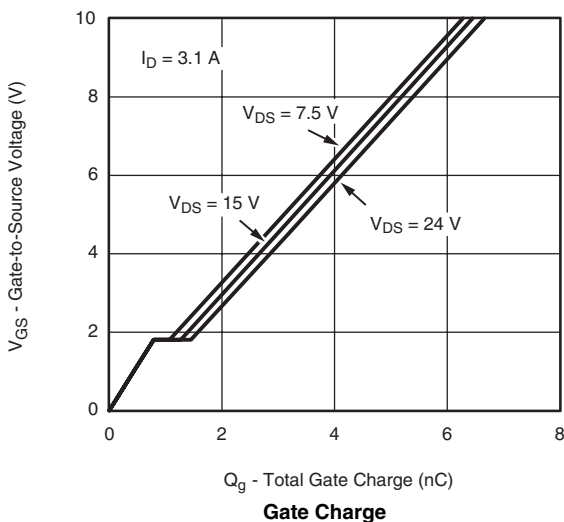
Transfer Characteristics



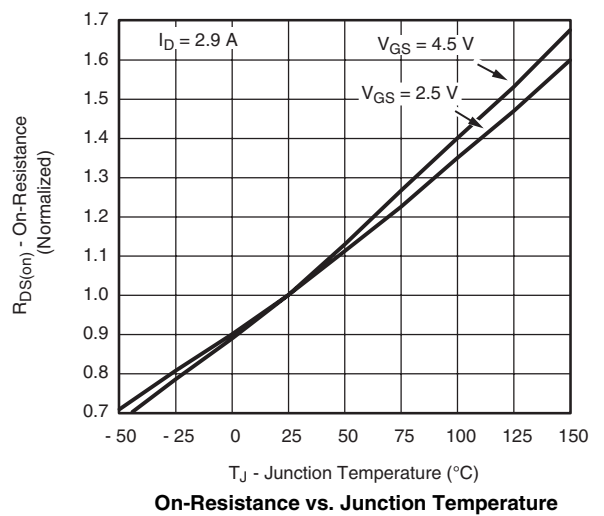
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



Gate Charge



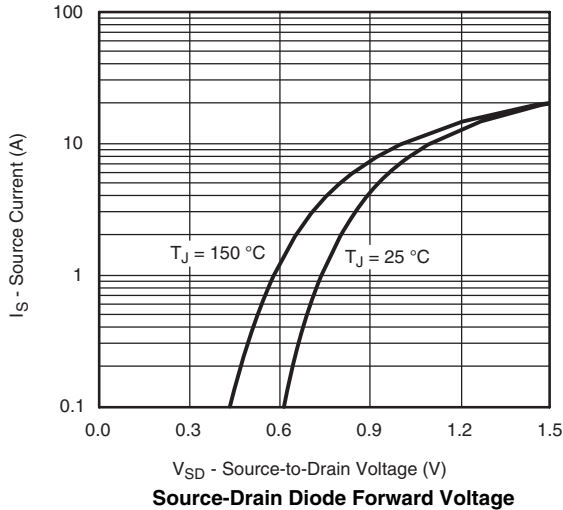
On-Resistance vs. Junction Temperature

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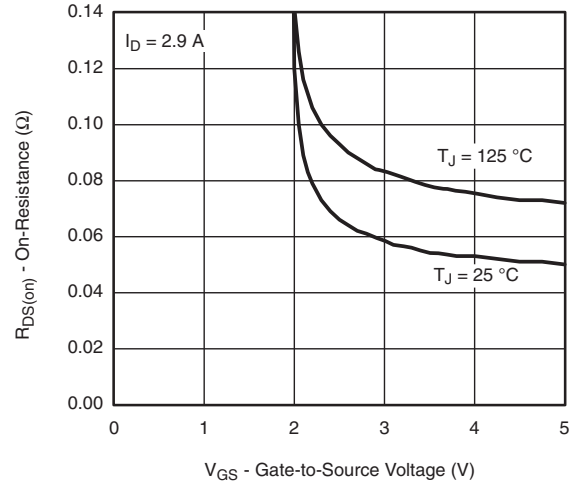
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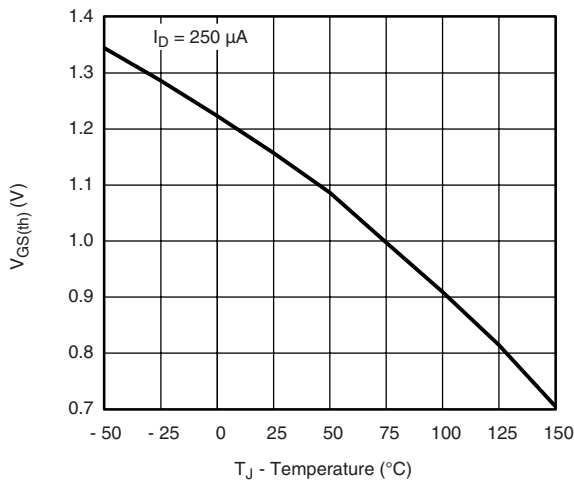
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



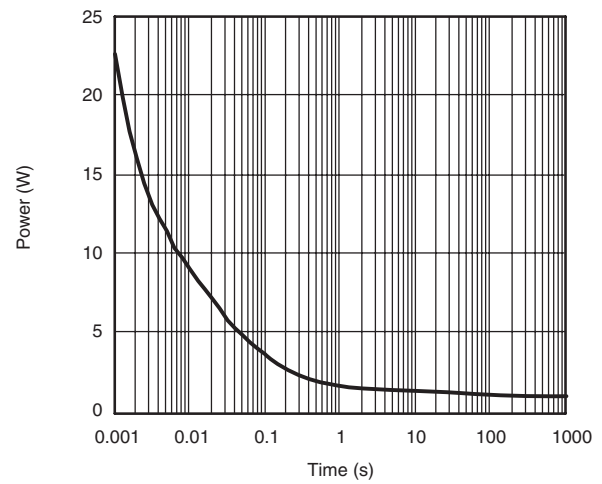
Source-Drain Diode Forward Voltage



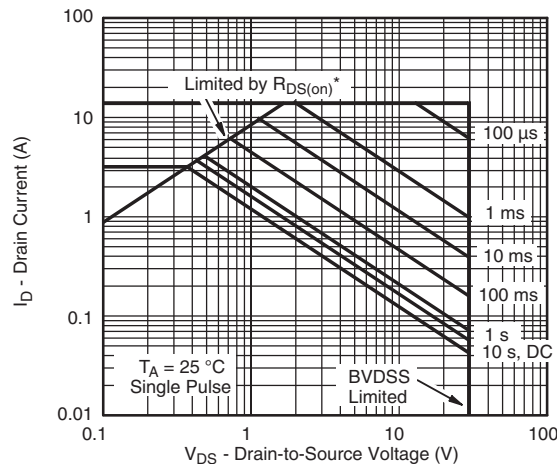
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power

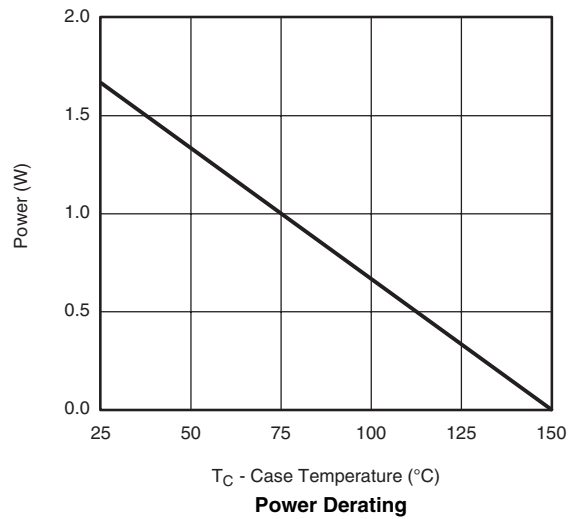
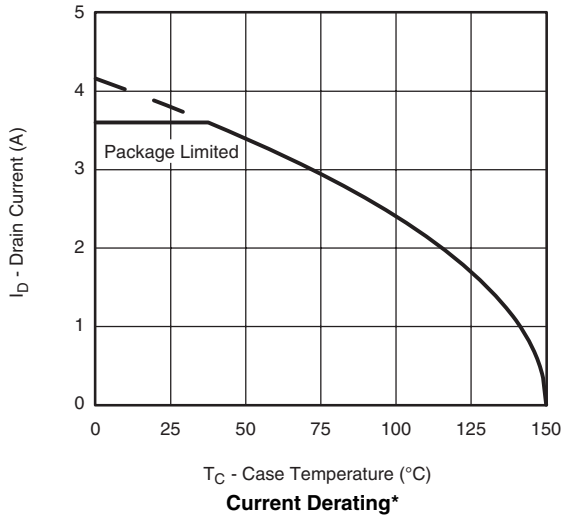


* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



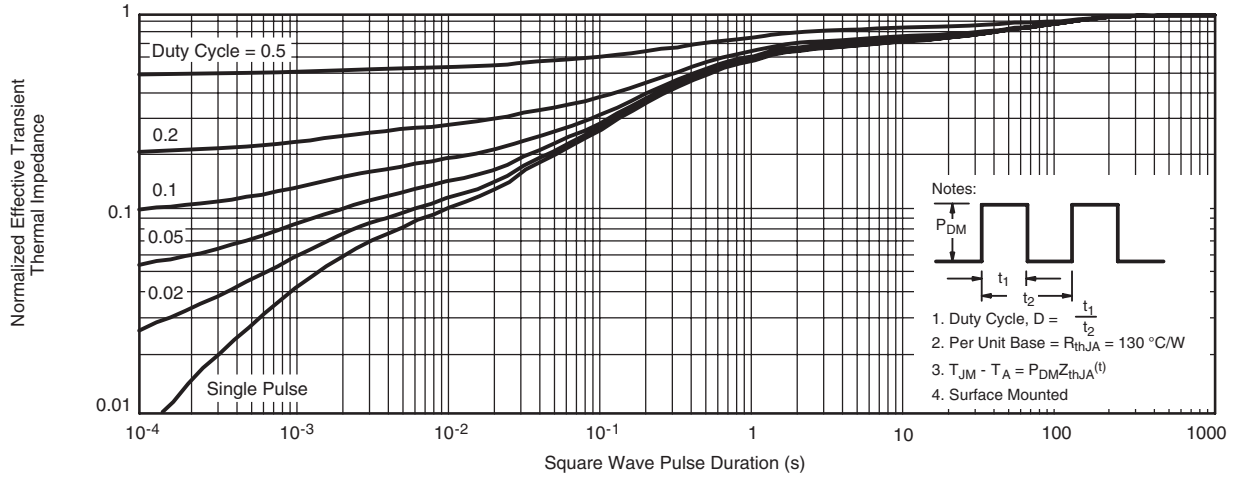
* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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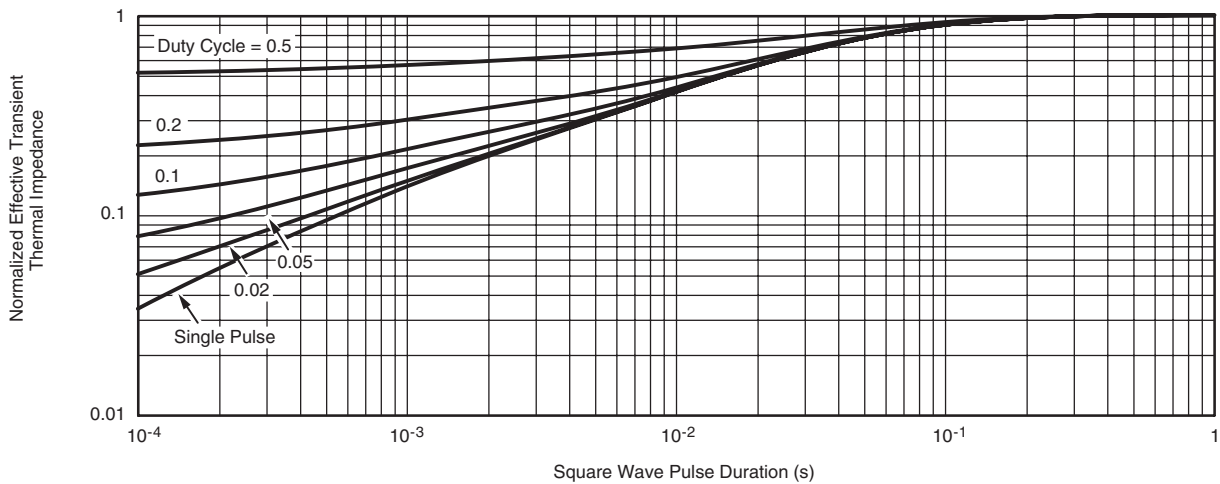
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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